16384-word×1-bit Dynamic Random Access Memory

The HM4816 is a new generation MOS dynamic RAM circuit organized as 16,384 words by 1 bit. As a state-of-the art MOS memory device, the HM4816 (16K RAM) incorporates advanced circuit techniques designed to provide wide operating margins, both internally and to the system user, while achieving performance levels in speed and power previously seen only in MOSTEK's high performance MK4027 (4K RAM).

The technology used to fabricate the HM4816 is HITACHI's double-poly, N-channel silicon gate process.

This process, coupled with the use of a single transistor dynamic storage cell provides the maximum possible circuit density and reliability, while maintaining high performance capability.

The use of dynamic circuitry throughout, including sense amplifiers, assures that power dissipation is minimized without any sacrifice in speed or operating margin. These factors combine to make the HM4816 a truly superior RAM product.

Multiplexed address inputs (a feature pioneered by MOSTEK for its 4K RAMs) permits the HM4816 to be packaged in a standard 16-pin DIP.

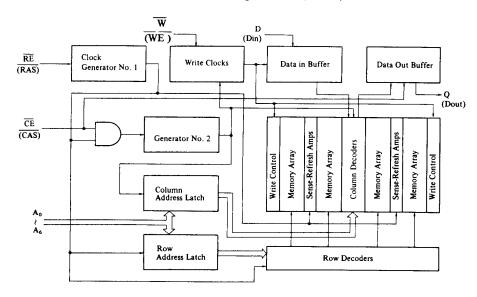
This recognized industry standard package configuration, while compatible with widely available automated testing and insertion equipment, provides highest possible system bit densities and simplifies system upgrade from 4K to 16K RAMs Non-critical clock timing requirements allow use of the multiplexing technique while maintaining high performance.

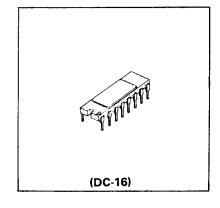
■ FEATURES

- Single 5V supply
- Low power standby and operation

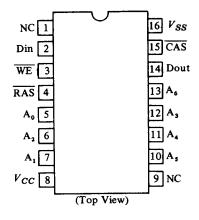
(Standby: 55mW max, operation: 440mW max)

- Fast access time & cycle time
 - (access time: 100ns max, cycle time: 200ns min)
- Directly TTL compatible: All inputs & outputs
- Output data controlled by CAS and unlatched at end of cycle to allow two dimensional chip selection and extended page boundary
- Common I/O capability using "early write" operation
- Read modify write, RAS only refresh and page mode capability





■ PIN ARRANGEMENT



ABSOLUTE MAXIMUM RATINGS

Item	Symbol	HM4816	Unit	
Voltage on any pin relative to GND	V_T	-1.0~+7.0	V	
Power supply voltage relative to GND	V _{CC}	-0.5~+7.0	V	
Short-circuit Output Current	Iout	50	m A	
Power Dissipation	P_T	1.0	W	
Operating Temperature	Topr	0~+70	°C	
Storage Temperature	T _{stg}	-65~+150	°C	

■ RECOMMENDED DC OPERATING CONDITIONS

Item	Symbol	min.	typ.	max.	Units	Notes
Supply voltage	V cc	4.5	5.0	5.5	V	1
	Vss	0	0	0	V	1,2
Input high(logic 1) voltage RAS, CAS, WE	V _{IH} c	2.7		6.0	V	1
Input high(logic 1) voltage except RAS, CAS, WE	V _{IH}	2.7		6.0	V	1
Input low(logic 0) voltage all inputs	V _{II} .	-1.0		0.8	V	1

Notes: 1. All voltages referenced to V_{SS} .

2. Output voltage will swing from V_{SS} to V_{CC} when activated with no current loading.

■ DC ELECTRICAL CHARACTERISTICS

Item	Symbol	Test Conditions	min.	typ.	max.	Unit
Operating current	Icci	\overline{RAS} , \overline{CAS} cycling, $t_{RC} = 200$ ns, Note 2		_	80	mA
Standby current	Icc 2	$\overline{RAS} = V_{IHC}$, Dout = high impedance		_	10	mA
Refresh current	Iccs	\overline{RAS} cycling, $\overline{CAS} = V_{IHC}$; $t_{RC} = 200$ ns	_		55	mA
Page mode current	Icc4	$\overline{RAS} = V_{IL}, \overline{CAS}$ cycling, $t_{PC} = 120$ ns; Note 2		_	55	mA
Input leakage current	$I_{I(L)}$	$V_{IN}=0$ to 6V, all other pins=0V	-10		10	μΑ
Output leakage current	Io (L)	V _{OUT} =0 to 5.5V, Dout is disabled	-10		10	μА
Output high voltage	Von	Note 1, $I_{out} = -5 \text{mA}$	2.4	_	Vcc	V
Output low voltage	Vol	$I_{OUT}=4.2\mathrm{mA}$	_	_	0.4	V

Notes: 1. Output voltage will swing from V_{SS} to V_{CC} when activated with no current loading.

 I_{CC1} and I_{CC4} depend upon output loading. During readout of high level data V_{CC} is connected through a low impedance (135Ω typ) to data out. At all other times I_{CC} consists of leakage currents only.

■ A.C. ELECTRICAL CHARACTERISTICS $(T_a=0 \text{ to } 70\%, V_{CC}=5.0\text{V}\pm10\%)$

Item	Symbol	min.	typ.	max.	Unit	Note
Random read or write cycle Time	t RC	200	_		ns	3
Read-write Cycle Time	t rwc	200			ns	3
Page Mode Cycle Time	t PC	120	_		ns	
Access Time from RAS	t RAC	_	_	100	ns	4,6
Access Time from CAS	tere			65	ns	5,6
Output Buffer Turn-off Delay	toff	0	_	25	ns	7
Transition Time (rise & fall)	tτ	3		25	ns	2
RAS Precharge	t RP	65			ns	
RAS Pulse Width	t RAS	100	_	10000	ns	
RAS Hold Time	t RSH	65	******		ns	
CAS Pulse Width	t C A S	65	_	10000	ns	
RAS to CAS Delay Time	t RCD	15		35	ns	8
CAS to RAS Precharge Time	t CRP	40		_	ns	
Row Address Set-up Time	t ASR	0	_	_	ns	
Row Address Hold Time	t RAH	15		_	ns	
Column Address Set-up Time	tasc	0	_	_	ns	
Column Address Hold Time	t CAH	35	_		ns	
Column Address Hold Time reference to RAS	t A R	70			ns	
Read Command Set-up Time	t RCS	0	_		ns	
Read Command Hold Time	t RCH	10	_	_	ns	
Write Command Hold Time	twc H	40		_	ns	
Write Command Hold Time reference to RAS	t we r	75	_	_	ns	
Write Command Pulse Width	twp	30	_	_	ns	
Write Command to RAS Lead Time	t RWL	45	_	_	ns	
Write Command to CAS Lead Time	t cw.	45	_		ns	
Data-in Set-up Time	t o s	0			ns	9
Data-in Hold Time	tын	40		_	ns	9
Data-in Hold Time reference to RAS	t D H R	75			ns	
CAS Precharge Time (for page mode cycle only)	t ∈ PP	40	_	_	ns	
Refresh Period	t REF	_		2	ns	
WE Command Set-up Time	twes	-10			ns	10
CAS to WE Delay	t CWD	45			ns	10
RAS to WE Delay	t RWD	80			ns	10
CAS Hold Time	t c s н	100	_		ns	

NOTES:

- 1. AC measurements assume $t_T = 5ns$.
- V_{IHC}(min) or V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also transition times are measured between V_{IHC} or V_{IH} and V_{IL}.
- 3. The specification for t_{RC} (min) and t_{RWC} (min) are used only to indicate cycle time at which proper operation over the full temperature range (0°C + $T_a \le 70$ °C) is assured.
- Assumes that t_{RCD} ≤ t_{RCD} (max.). If t_{RCD} is greater than the maximum recommended value shown in this table, t_{RAC} will increase by the amount that t_{RCD} exceeds the value shown.
- 5. Assumes that $t_{RCD} \ge t_{RCD}$ (max).
- Measured with a load equivalent to 2 TTL loads and 100pF.
- tOFF (max) defines the time at which the output achieves the open circuit condition and is not referenced to output voltage levels.

- Operation within the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC}.
- These parameters are referenced to CAS leading edge in early write cycles and to WE leading edge in delayed write or readmodify-write cycles.
- 10.twcs, tcwD and trwD are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only; If twcs ≥ twcs (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; If tcwD ≥ tcwD (min) and trwD ≥ trwD (min), the cycle is a read-write cycle and the data out will contain data read from the selected cell; If neither of the above sets of conditions is satisfied the condition of the data out (at access time) is indeterminate.



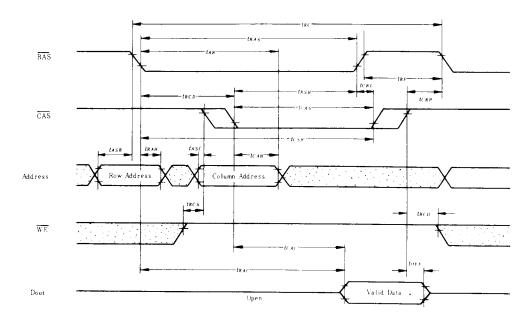
■ CAPACITANCE $(Ta=0 \text{ to } 70\%, Vcc=5.0V\pm10\%)$

Item	Symbol	min.	typ.	max.	Unit	Note
Input Capacitance (Ao to Ao), Din	C11		4	6	pF	1
Input Capacitance RAS, CAS, WE	C12		5	7	pF	2
Output Capacitance (Dout)	<i>C</i> o	_	5	7	pF	2,3

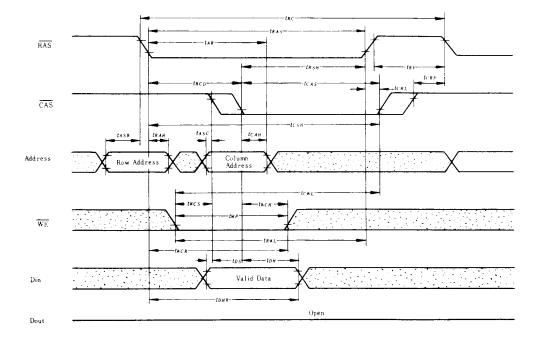
Notes: 1. Effective capacitance calculated from the equation $C = I \circ \Delta t / \Delta V$ with $\Delta V = 3V$ and power supplies at nominal levels.

2. $\overline{CAS} = V_{IHC}$ to disable D_{OUT} .

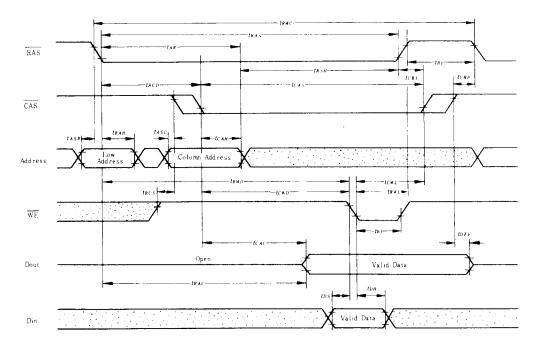
• READ CYCLE



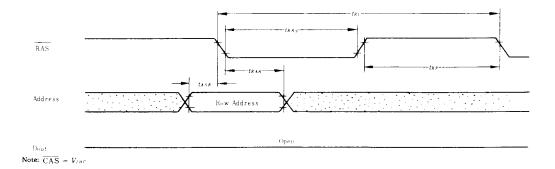
WRITE CYCLE



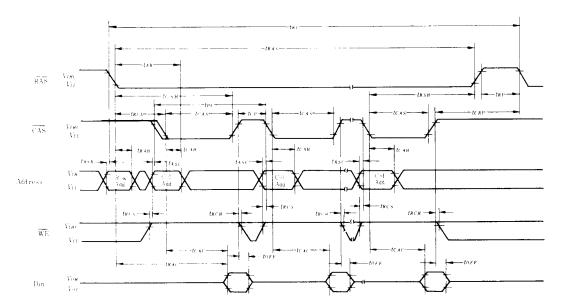
• READ-WRITE/READ-MODIFY-WRITE CYCLE



• RAS-ONLY" REFRESH CYCLE



• PAGE MODE READ CYCLE



• PAGE MODE WRITE CYCLE

